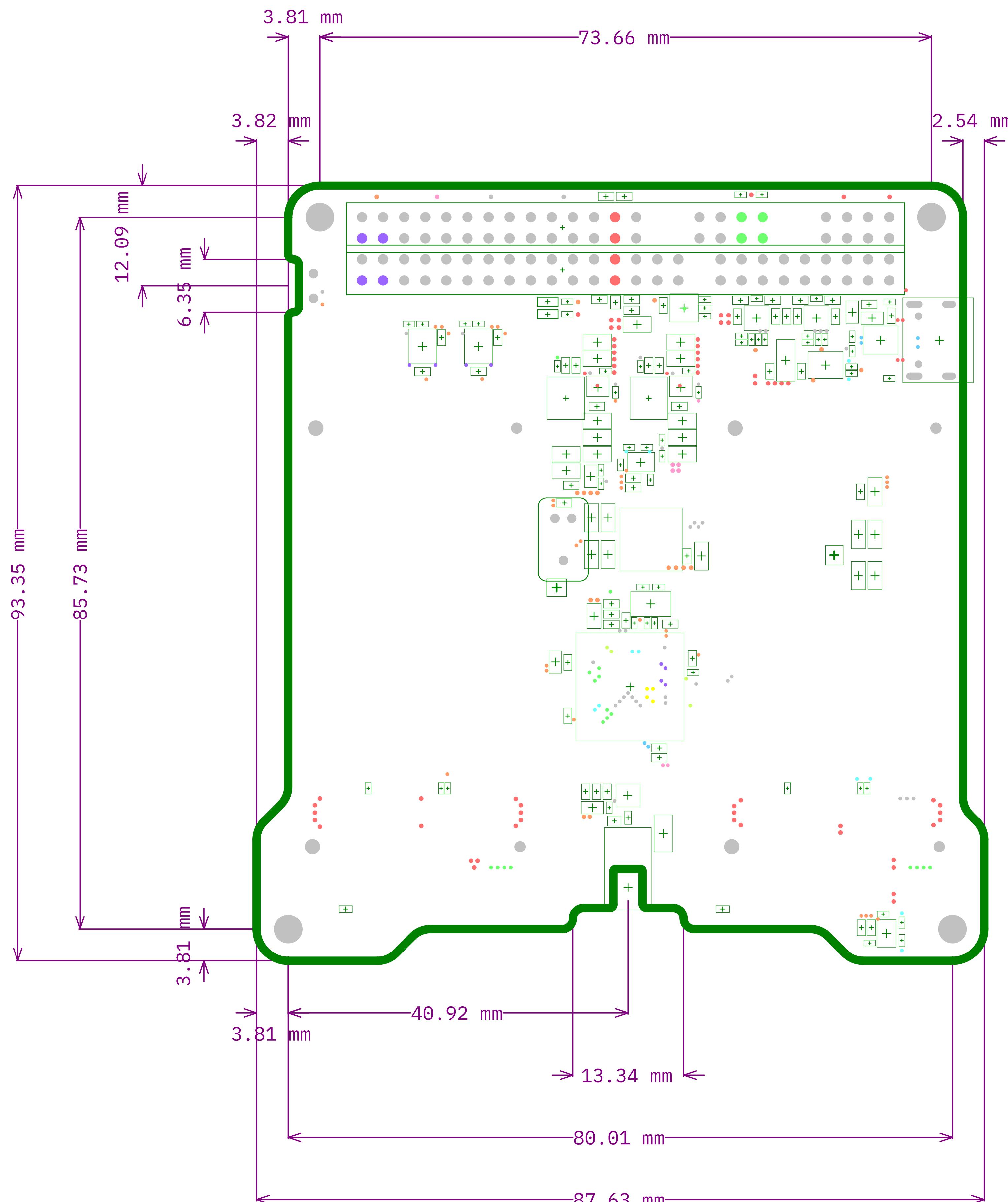


Layer	Name	Material	Thickness	Constant	Gerber
	Top Overlay				GTO
	Top Solder	SM-001	0.025mm	4	GTS
1	Top	CF-003	0.018mm		GTL
	PP-top	PP-008	0.220mm	4.1	
2	GND-1	CF-004	0.035mm		GP1
	Core 1	Core-009	0.350mm	4.5	
3	Layer 1	CF-004	0.035mm		G1
	PP-mid	PP-008	0.220mm	4.1	
4	Layer 2	CF-004	0.035mm		G2
	Core 2	Core-009	0.350mm	4.5	
5	GND-2	CF-004	0.035mm		GP2
	PP-bottom	PP-008	0.220mm	4.1	
6	Bottom	CF-003	0.018mm		GBL
	Board Layer Stack Bottom Solder	SM-001	0.025mm	4	GBS
	Board Layer Stack Bottom Overlay				GBO

Total board thickness: 1.586mm

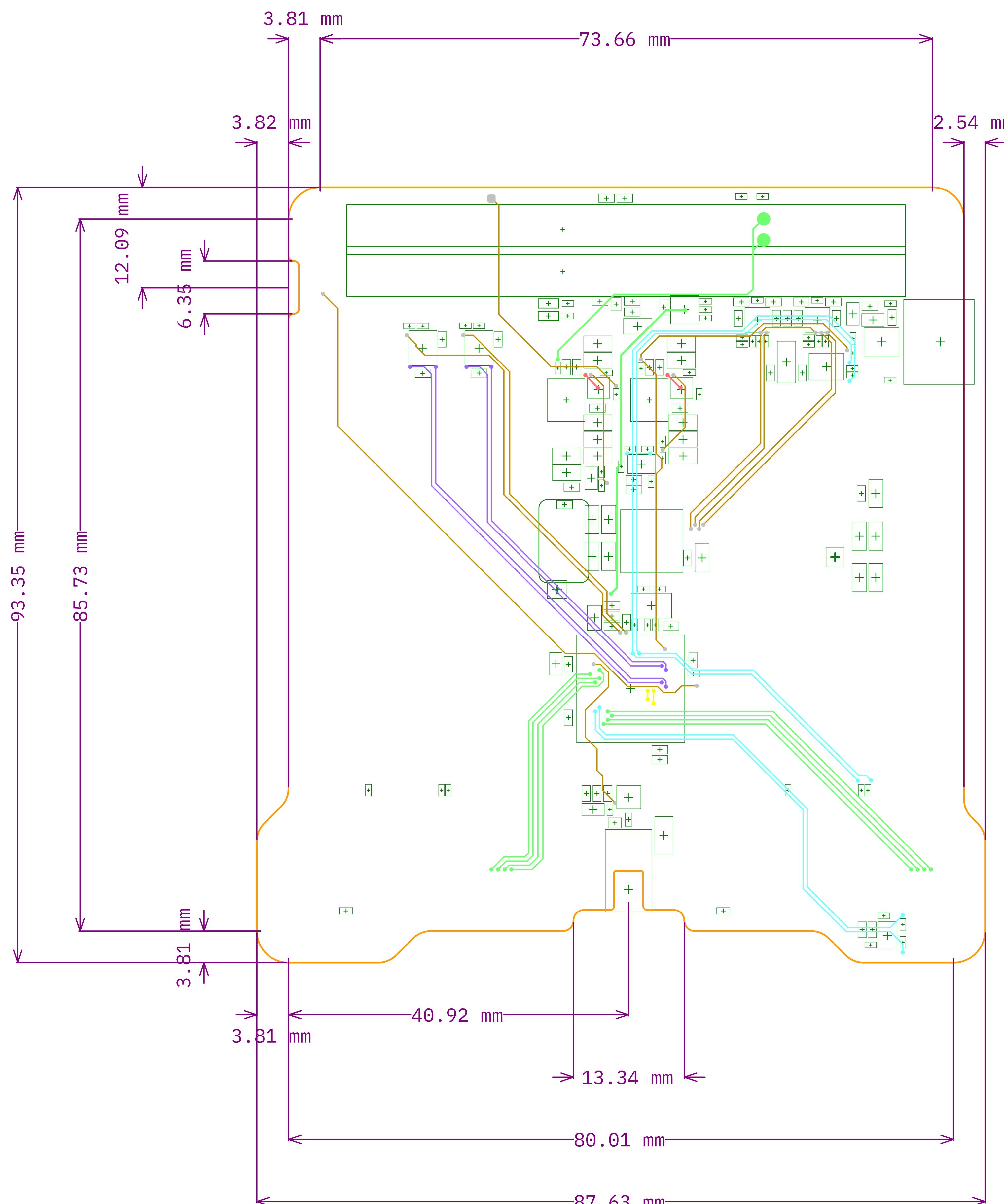
Pluton UPV	
Project: Estigia Comms Payload - Cubesat carrier	
Layer: Board Shape Component Guard Component Guard Dimension	
Engineer: Juan Del Pino Mena	
Date: 2024-08-11	Revision: 0.4
Size: A4	



Layer	Name	Material	Thickness	Constant	Gerber
	Top Overlay				GTO
	Top Solder	SM-001	0.025mm	4	GTS
1	Top	CF-003	0.018mm		GTL
	PP-top	PP-008	0.220mm	4.1	
2	GND-1	CF-004	0.035mm		GP1
	Core 1	Core-009	0.350mm	4.5	
3	Layer 1	CF-004	0.035mm		G1
	PP-mid	PP-008	0.220mm	4.1	
4	Layer 2	CF-004	0.035mm		G2
	Core 2	Core-009	0.350mm	4.5	
5	GND-2	CF-004	0.035mm		GP2
	PP-bottom	PP-008	0.220mm	4.1	
6	Bottom	CF-003	0.018mm		GBL
	Board Layer Stack Bottom Solder	SM-001	0.025mm	4	GBS
	Board Layer Stack Bottom Overlay				GBO

Total board thickness: 1.586mm

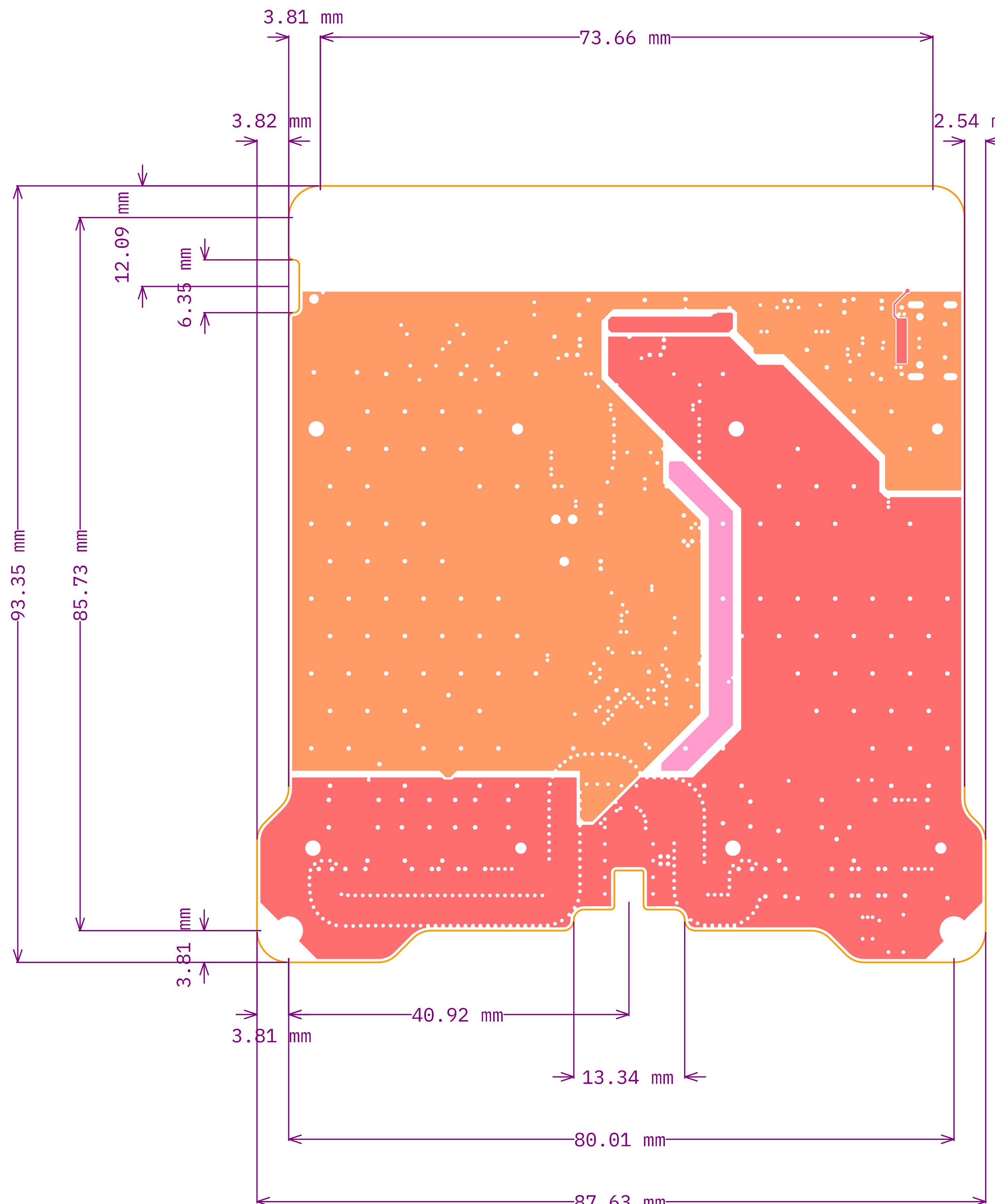
Pluton UPV	Project: Estigia Comms Payload - Cubesat carrier	Board Shape: Component Guard	Component Guard Dimension	PLUTON
Layer: Component Guard				
Engineer: Juan Del Pino Mena				
Date: 2024-08-11	Revision: 0.4			Size: A4



Layer	Name	Material	Thickness	Constant	Gerber
	Top Overlay				GTO
	Top Solder	SM-001	0.025mm	4	GTS
1	Top	CF-003	0.018mm		GTL
	PP-top	PP-008	0.220mm	4.1	
2	GND-1	CF-004	0.035mm		GP1
	Core 1	Core-009	0.350mm	4.5	
3	Layer 1	CF-004	0.035mm		G1
	PP-mid	PP-008	0.220mm	4.1	
4	Layer 2	CF-004	0.035mm		G2
	Core 2	Core-009	0.350mm	4.5	
5	GND-2	CF-004	0.035mm		GP2
	PP-bottom	PP-008	0.220mm	4.1	
6	Bottom	CF-003	0.018mm		GBL
	Board Layer Stack Bottom Solder	SM-001	0.025mm	4	GBS
	Board Layer Stack Bottom Overlay				GBO

Total board thickness: 1.586mm

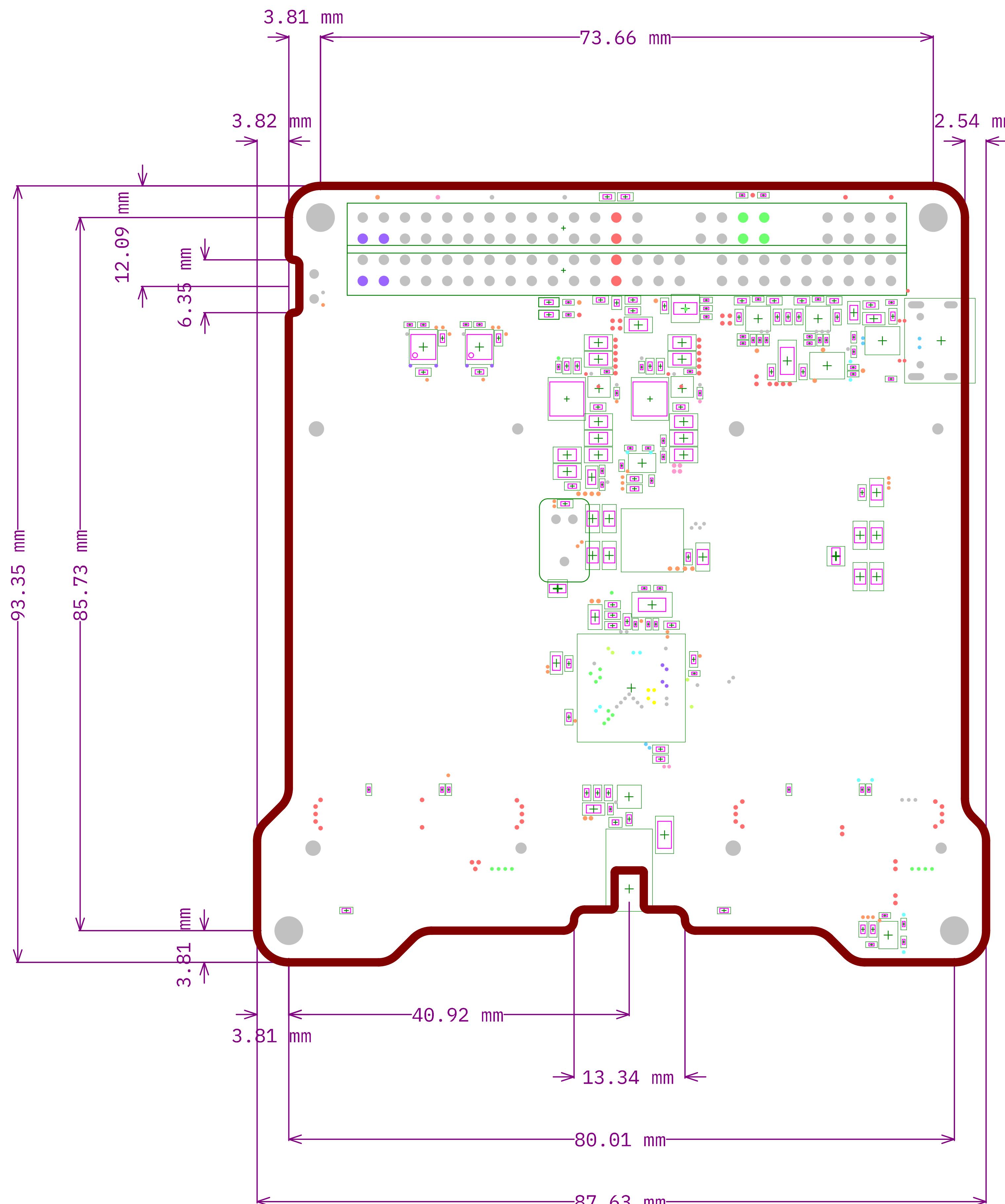
Pluton UPV	Project: Estigia Comms Payload - Cubesat carrier	Board Shape: Component Guard
Layer: Component Guard	Component Guard Dimension	
Engineer: Juan Del Pino Mena		
Date: 2024-08-11	Revision: 0.4	Size: A4



Layer	Name	Material	Thickness	Constant	Gerber
	Top Overlay				GTO
	Top Solder	SM-001	0.025mm	4	GTS
1	Top	CF-003	0.018mm		GTL
	PP-top	PP-008	0.220mm	4.1	
2	GND-1	CF-004	0.035mm		GP1
	Core 1	Core-009	0.350mm	4.5	
3	Layer 1	CF-004	0.035mm		G1
	PP-mid	PP-008	0.220mm	4.1	
4	Layer 2	CF-004	0.035mm		G2
	Core 2	Core-009	0.350mm	4.5	
5	GND-2	CF-004	0.035mm		GP2
	PP-bottom	PP-008	0.220mm	4.1	
6	Bottom	CF-003	0.018mm		GBL
	Board Layer Stack Bottom Solder	SM-001	0.025mm	4	GBS
	Board Layer Stack Bottom Overlay				GBO

Total board thickness: 1.586mm

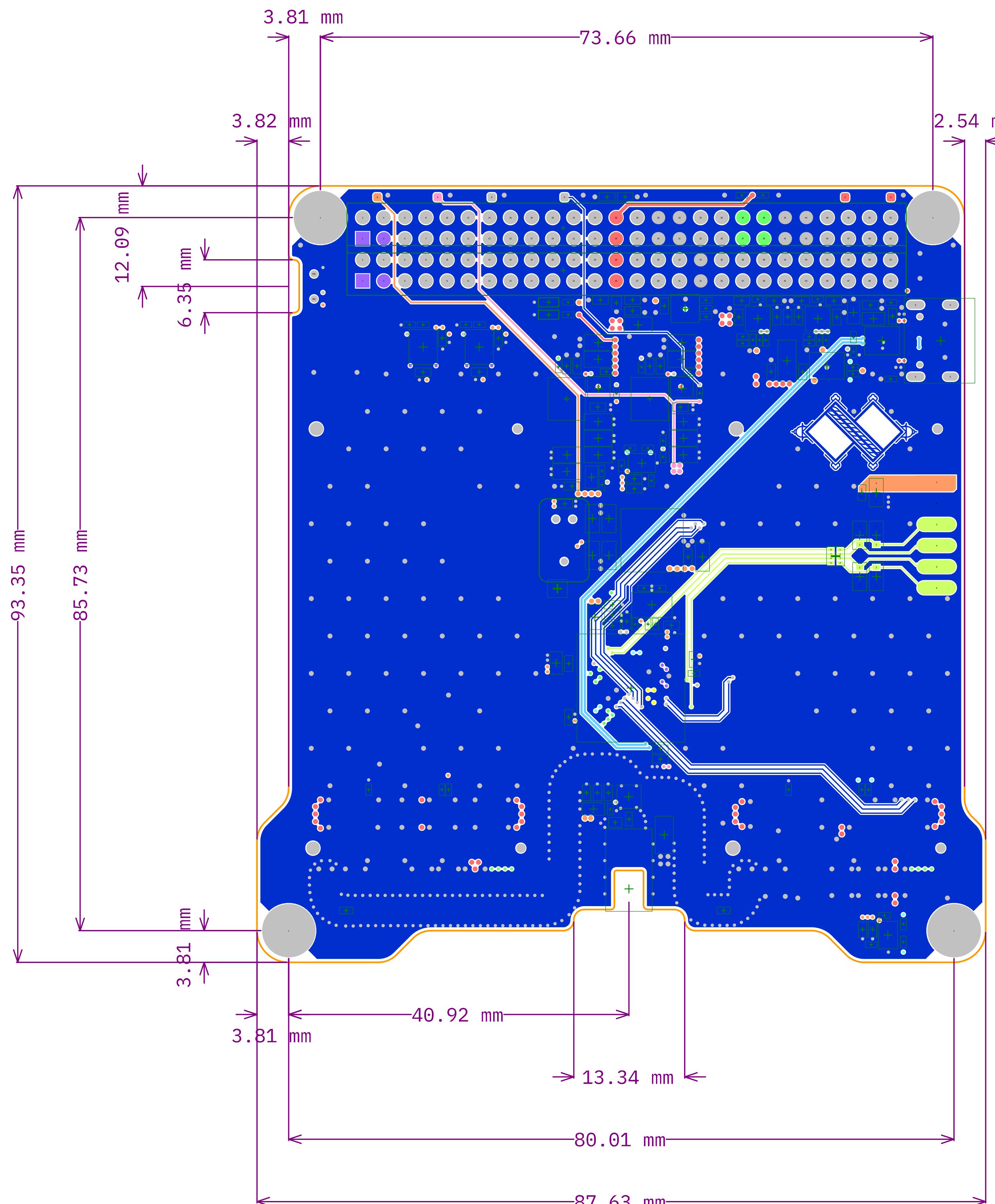
Pluton UPV	Dimension	PLUTON
Project: Estigia Comms Payload - Cubesat carrier		
Layer: Board Shape		
Engineer: Juan Del Pino Mena		
Date: 2024-08-11	Revision: 0.4	Size: A4



Layer	Name	Material	Thickness	Constant	Gerber
	Top Overlay				GTO
	Top Solder	SM-001	0.025mm	4	GTS
1	Top	CF-003	0.018mm		GTL
	PP-top	PP-008	0.220mm	4.1	
2	GND-1	CF-004	0.035mm		GP1
	Core 1	Core-009	0.350mm	4.5	
3	Layer 1	CF-004	0.035mm		G1
	PP-mid	PP-008	0.220mm	4.1	
4	Layer 2	CF-004	0.035mm		G2
	Core 2	Core-009	0.350mm	4.5	
5	GND-2	CF-004	0.035mm		GP2
	PP-bottom	PP-008	0.220mm	4.1	
6	Bottom	CF-003	0.018mm		GBL
	Board Layer Stack Bottom Solder	SM-001	0.025mm	4	GBS
	Board Layer Stack Bottom Overlay				GBO

Total board thickness: 1.586mm

Pluton UPV	Project: Estigia Comms Payload - Cubesat carrier	PLUTON
Layer: Component Guard	Component Guard Dimension	
Board Shape	Component Guard	
Engineer: Juan Del Pino Mena		
Date: 2024-08-11	Revision: 0.4	Size: A4

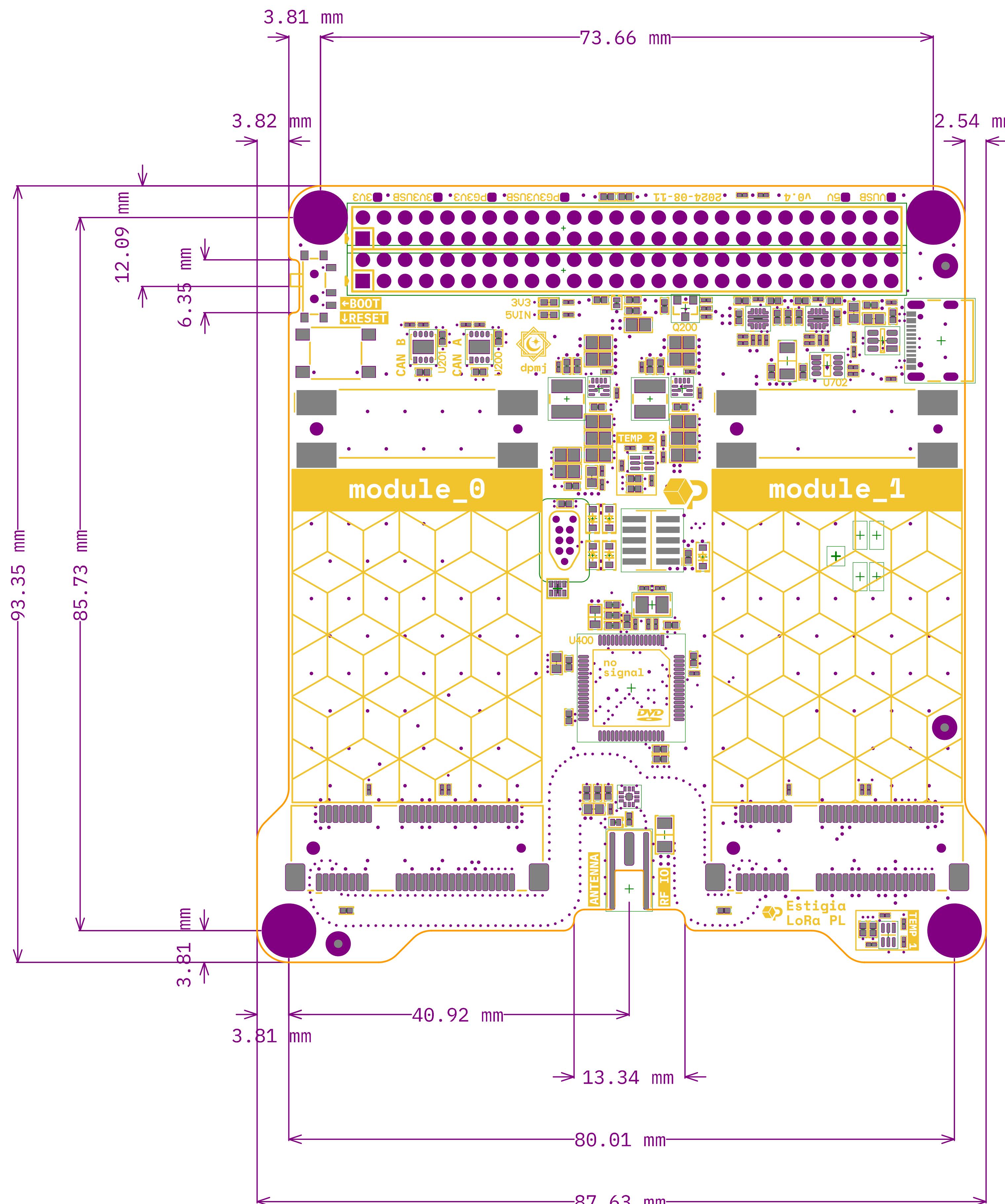


Layer	Name	Material	Thickness	Constant	Gerber
	Top Overlay				GTO
	Top Solder	SM-001	0.025mm	4	GTS
1	Top	CF-003	0.018mm		GTL
	PP-top	PP-008	0.220mm	4.1	
2	GND-1	CF-004	0.035mm		GP1
	Core 1	Core-009	0.350mm	4.5	
3	Layer 1	CF-004	0.035mm		G1
	PP-mid	PP-008	0.220mm	4.1	
4	Layer 2	CF-004	0.035mm		G2
	Core 2	Core-009	0.350mm	4.5	
5	GND-2	CF-004	0.035mm		GP2
	PP-bottom	PP-008	0.220mm	4.1	
6	Bottom	CF-003	0.018mm		GBL
	Board Layer Stack Bottom Solder	SM-001	0.025mm	4	GBS
	Board Layer Stack Bottom Overlay				GBO

Total board thickness: 1.586mm

Pluton UPV	Project: Estigia Comms Payload - Cubesat carrier	Board Shape: Component Guard
Layer: Component Guard	Component Guard Dimension	
Engineer: Juan Del Pino Mena		
Date: 2024-08-11	Revision: 0.4	Size: A4

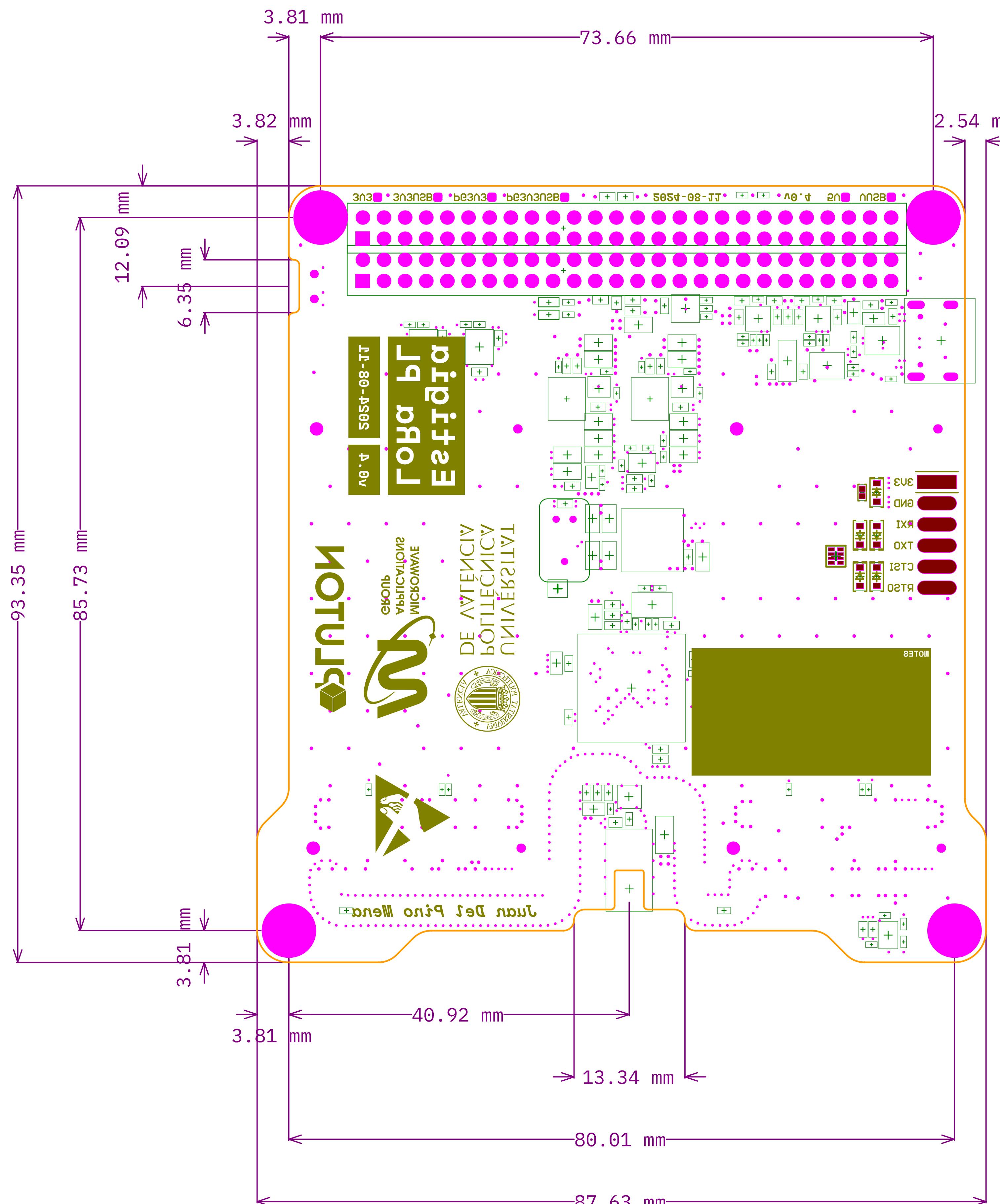
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Layer	Name	Material	Thickness	Constant	Gerber
	Top Overlay				GTO
	Top Solder	SM-001	0.025mm	4	GTS
1	Top	CF-003	0.018mm		GTL
	PP-top	PP-008	0.220mm	4.1	
2	GND-1	CF-004	0.035mm		GP1
	Core 1	Core-009	0.350mm	4.5	
3	Layer 1	CF-004	0.035mm		G1
	PP-mid	PP-008	0.220mm	4.1	
4	Layer 2	CF-004	0.035mm		G2
	Core 2	Core-009	0.350mm	4.5	
5	GND-2	CF-004	0.035mm		GP2
	PP-bottom	PP-008	0.220mm	4.1	
6	Bottom	CF-003	0.018mm		GBL
	Board Layer Stack Bottom Solder	SM-001	0.025mm	4	GBS
	Board Layer Stack Bottom Overlay				GBO

Total board thickness: 1.586mm

Pluton UPV	
Project: Estigia Comms Payload - Cubesat carrier	
Layer: Board Shape, Component Guard, Component Guard, Top Dimension	
Engineer: Juan Del Pino Mena	
Date: 2024-08-11	Revision: 0.4
Size: A4	

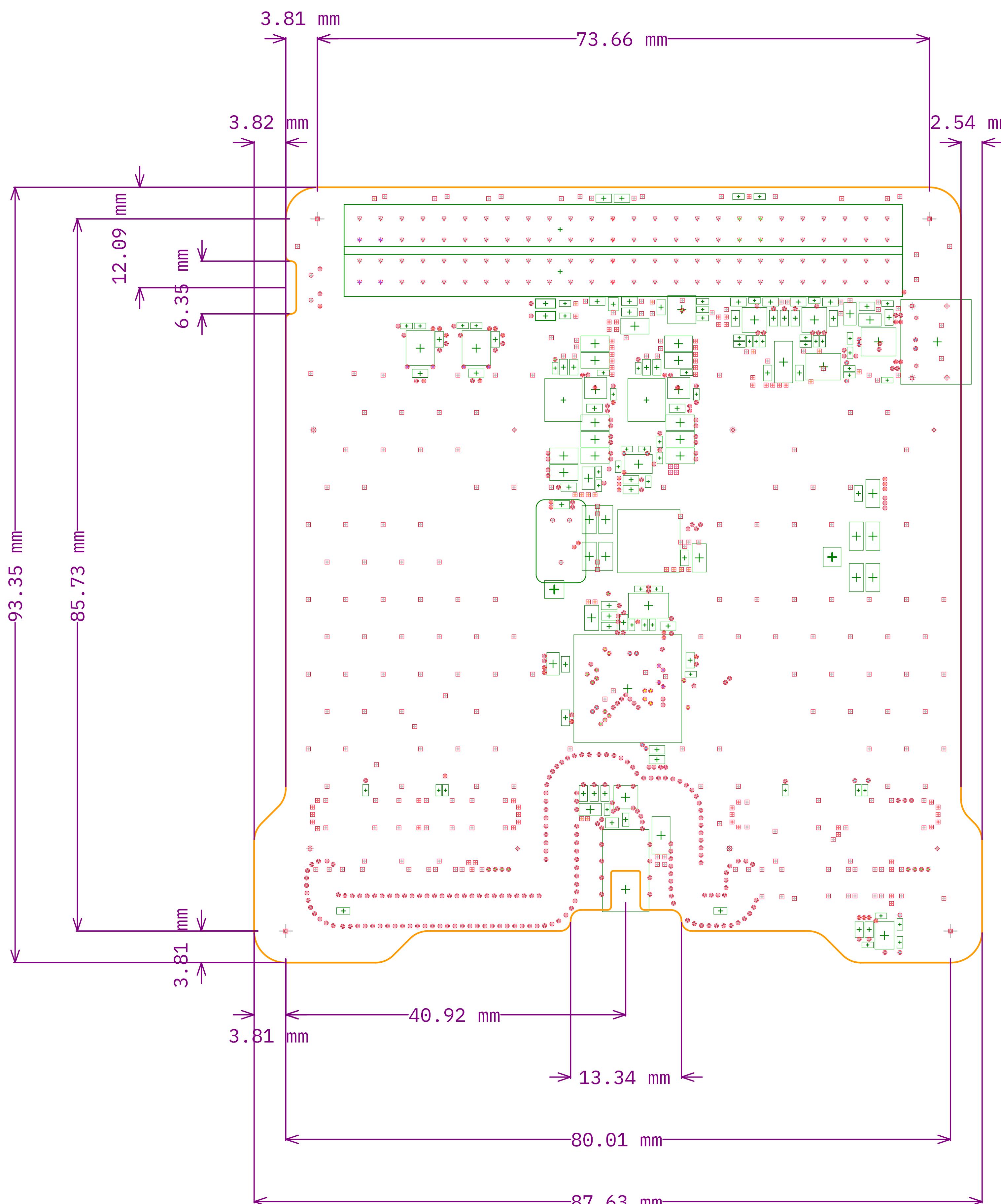


Layer	Name	Material	Thickness	Constant	Gerber
	Top Overlay				GTO
	Top Solder	SM-001	0.025mm	4	GTS
1	Top	CF-003	0.018mm		GTL
	PP-top	PP-008	0.220mm	4.1	
2	GND-1	CF-004	0.035mm		GP1
3	Layer 1	CF-004	0.035mm		G1
	PP-mid	PP-008	0.220mm	4.1	
4	Layer 2	CF-004	0.035mm		G2
	Core 2	Core-009	0.350mm	4.5	
5	GND-2	CF-004	0.035mm		GP2
	PP-bottom	PP-008	0.220mm	4.1	
6	Bottom	CF-003	0.018mm		GBL
	Board Layer Stack Bottom Solder	SM-001	0.025mm	4	GBS
	Board Layer Stack Bottom Overlay				GBO

Total board thickness: 1.586mm

Pluton UPV	Board Shape Bottom Overlay Bottom Paste Guard Board Layer Dimension Solder	Size: A4
Project: Estigia Comms Payload - Cubesat carrier		
Layer: Bottom Paste Guard		
Engineer: Juan Del Pino Mena		
Date: 2024-08-11	Revision: 0.4	

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Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template
○	397	0.200mm	PTH	Round	Top - Bottom	Via	Rounded	(Mixed)
□	323	0.300mm	PTH	Round	Top - Bottom	(Mixed)	(Mixed)	
☆	2	0.650mm	NPTH	Round	Top - Bottom	Pad	Rounded	c65hn65m65p0
○	5	0.900mm	NPTH	Round	Top - Bottom	Pad	Rounded	(Mixed)
▽	104	1.000mm	PTH	Round	Top - Bottom	Pad	(Mixed)	(Mixed)
◇	4	1.100mm	NPTH	Round	Top - Bottom	Pad	Rounded	c110hn110m110p0
+	2	1.400mm	PTH	Slot	Top - Bottom	Pad	Rounded Rectangle	r100_180h140_60r50m100_180p0
×	4	1.600mm	NPTH	Round	Top - Bottom	Pad	Rounded	c160hn160m160p0
✗	2	1.700mm	PTH	Slot	Top - Bottom	Pad	Rounded Rectangle	r100_210h170_60r50m100_210p0
□	4	3.200mm	PTH	Round	Top - Bottom	Pad	Rounded	c640h320_503323056
847 Total								

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Layer	Name	Material	Thickness	Constant	Gerber
	Top Overlay				GTO
	Top Solder	SM-001	0.025mm	4	GTS
1	Top	CF-003	0.018mm		GTL
	PP-top	PP-008	0.220mm	4.1	
2	GND-1	CF-004	0.035mm		GP1
	Core 1	Core-009	0.350mm	4.5	
3	Layer 1	CF-004	0.035mm		G1
	PP-mid	PP-008	0.220mm	4.1	
4	Layer 2	CF-004	0.035mm		G2
	Core 2	Core-009	0.350mm	4.5	
5	GND-2	CF-004	0.035mm		GP2
	PP-bottom	PP-008	0.220mm	4.1	
6	Bottom	CF-003	0.018mm		GBL
	Board Layer Stack Bottom Solder	SM-001	0.025mm	4	GBS
	Board Layer Stack Bottom Overlay				GBO

Total board thickness: 1.586mm

Pluton UPV	
Project: Estigia Comms Payload - Cubesat carrier	
Layer: Board Shape Component Guard Drill Drawing Drill Guide Dimension	
Engineer: Juan Del Pino Mena	
Date: 2024-08-11	Revision: 0.4
Size: A4	

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